

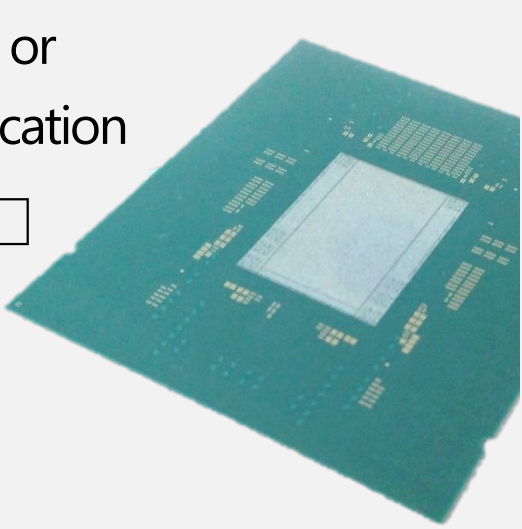
Advanced LSI Test Board

Chip Test Boards with FC-BGA and Ultra-High Multilayer Substrate Technologies

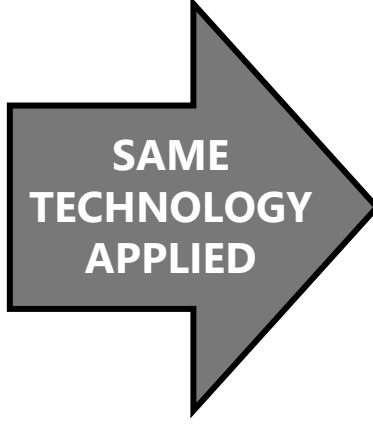
High Performance Space Transformer Substrate

Large FC-BGA substrate

Large Substrate Suitable for Large Die or Chiplet Application
>100mm□

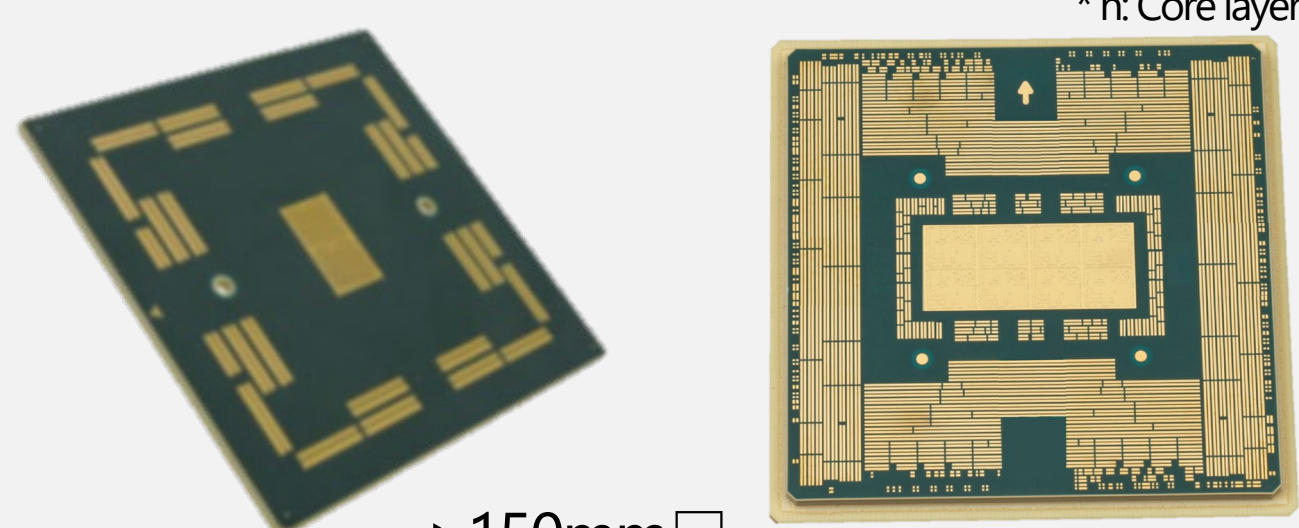


SAME TECHNOLOGY APPLIED



ST BOARD

* n: Core layer

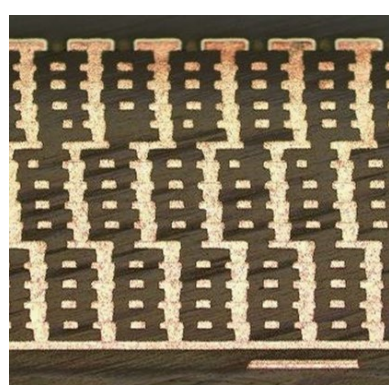


>150mm□

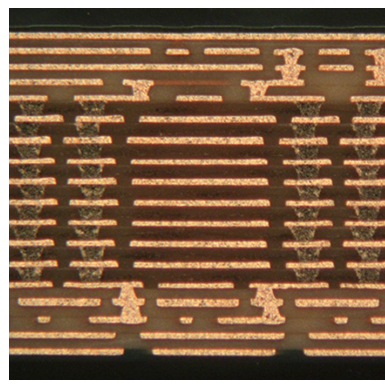
Features
>150mm□ size of 16-n*-16 buildup substrate is available.

■ Multilayer buildup structure based on FC-BGA SAP*

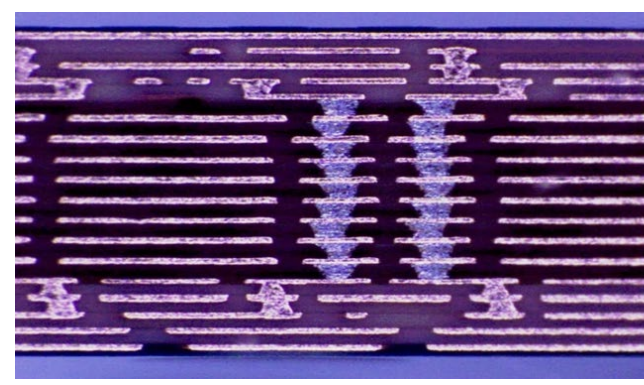
*Semi Additive Process



16 layers buildup



Any layer IVH with our F-ALCS Technology

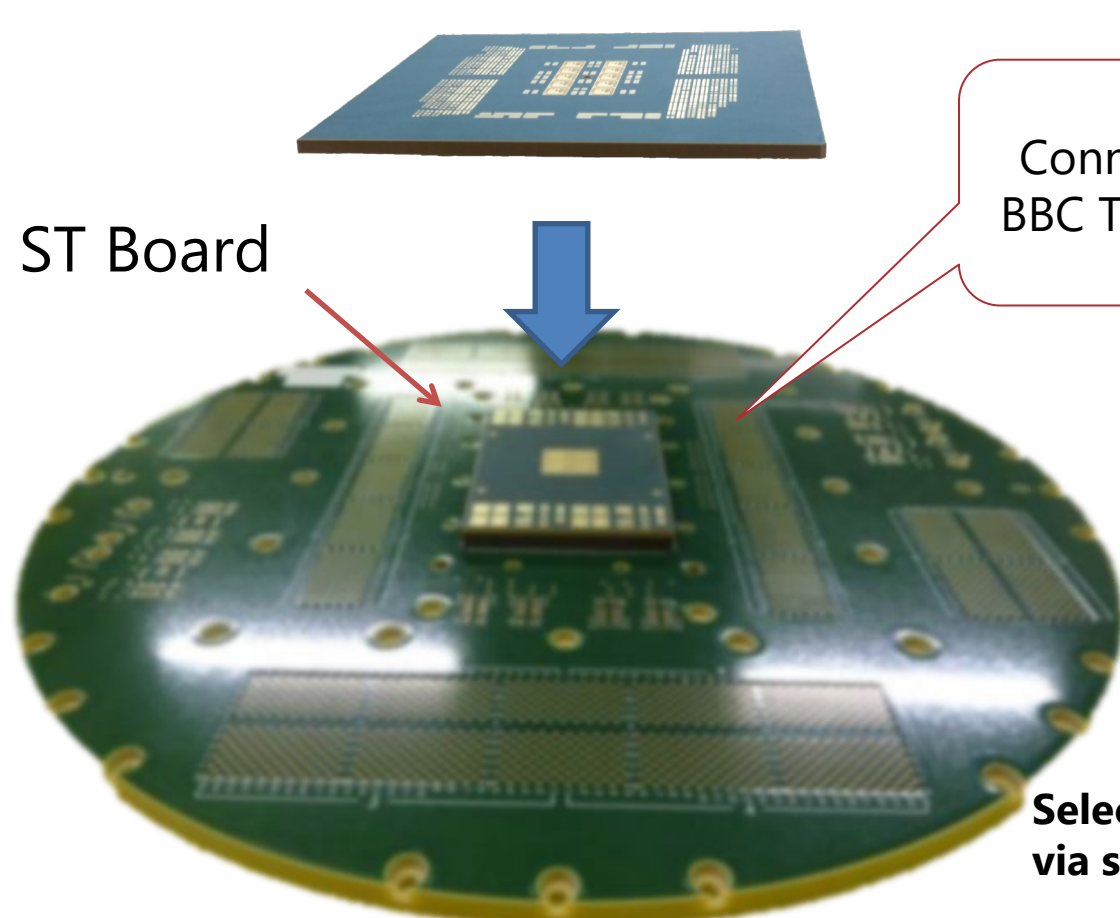


Buildup layers
F-ALCS Core
Buildup layers

ST Substrate and Ultra-High Multilayer Substrate Structure

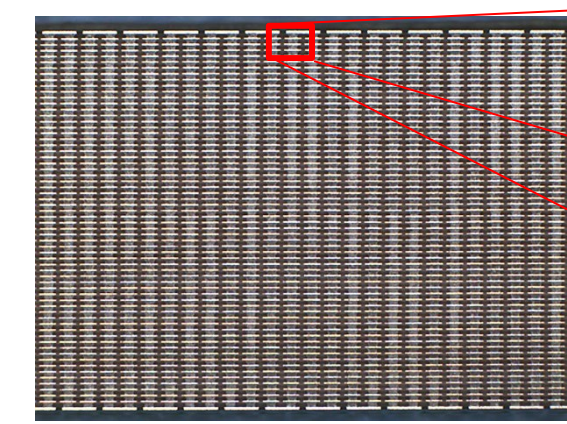
- FC-BGA substrate technology and ultra-high multilayer substrate technology
- Via structures for ultra-high multilayer + ultra-high aspect structures

ST Board



Connected by BBC Technology

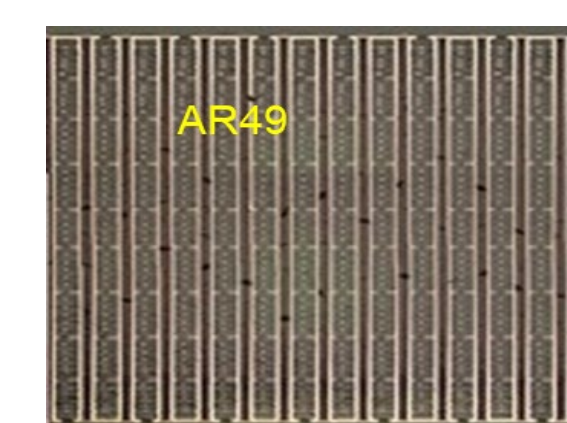
Selection of main board via structure



Any layer IVH structure (F-ALCS)

[Sample Specifications]

- Layers : 64 layers
- Thickness : 7.4mm
- Via Pitch : 0.365mm



High aspect through hole structure

[Sample Specifications]

- Layers : 106 layers
- Thickness : 7.4mm
- Via Pitch : 0.4mm

